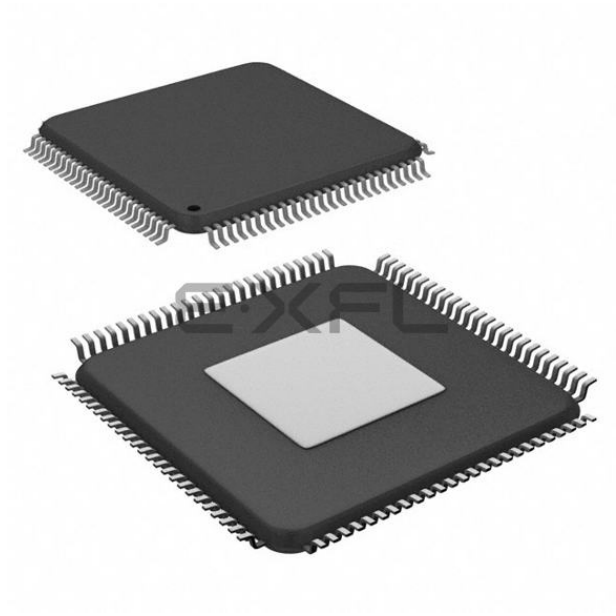
Infineon Technologies - SAK-XC2365-72F66L AC Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	C166SV2
Core Size	16/32-Bit
Speed	66MHz
Connectivity	CANbus, EBI/EMI, I²C, LINbus, SPI, SSC, UART/USART, USI
Peripherals	I²S, POR, PWM, WDT
Number of I/O	75
Program Memory Size	576KB (576K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	50K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP Exposed Pad
Supplier Device Package	PG-LQFP-100-3
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/sak-xc2365-72f66l-ac

Table 1 XC2365 Derivative Synopsis

Derivative[1]	Temp. Range	Program Memory[2]	PSRAM[3]	CCU6 Mod.	ADC[4] Chan.	Interfaces[4]
SAK-XC2365-72FxxL	-40 °C to 125 °C	576 Kbytes Flash	32 Kbytes	0, 1	11 + 5	3 CAN Nodes, 6 Serial Chan.
SAF-XC2365-72FxxL	-40 °C to 85 °C	576 Kbytes Flash	32 Kbytes	0, 1	11 + 5	3 CAN Nodes, 6 Serial Chan.
SAK-XC2365-56FxxL	-40 °C to 125 °C	448 Kbytes Flash	16 Kbytes	0, 1	11 + 5	3 CAN Nodes, 6 Serial Chan.
SAF-XC2365-56FxxL	-40 °C to 85 °C	448 Kbytes Flash	16 Kbytes	0, 1	11 + 5	3 CAN Nodes, 6 Serial Chan.
SAK-XC2365-48FxxL	-40 °C to 125 °C	384 Kbytes Flash	8 Kbytes	0, 1	11 + 5	3 CAN Nodes, 6 Serial Chan.
SAF-XC2365-48FxxL	-40 °C to 85 °C	384 Kbytes Flash	8 Kbytes	0, 1	11 + 5	3 CAN Nodes, 6 Serial Chan.

1) This Data Sheet is valid for devices starting with and including design step AC.

2) Specific inormation about the on-chip Flash memory in **Table 2**.

3) All derivatives additionally provide 1 Kbyte SBRAM, 2 Kbytes DPRAM, and 16 Kbytes DSRAM.

4) Specific information about the available channels in **Table 3**.
Analog input channels are listed for each Analog/Digital Converter module separately (ADC0 + ADC1).

Table 4 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
10	V_{DDIM}	-	PS/M	**Digital Core Supply Voltage for Domain M** Decouple with a ceramic capacitor, see **Table 12** for details.
38, 64, 88	V_{DDI1}	-	PS/1	**Digital Core Supply Voltage for Domain 1** Decouple with a ceramic capacitor, see **Table 12** for details. All V_{DDI1} pins must be connected to each other.
14	V_{DDPA}	-	PS/A	**Digital Pad Supply Voltage for Domain A** Connect decoupling capacitors to adjacent V_{DDP}/V_{SS} pin pairs as close as possible to the pins. *Note: The A/D_Converters and ports P5, P6, and P15 are fed from supply voltage V_{DDPA}.*
2, 25, 27, 50, 52, 75, 77, 100	V_{DDPB}	-	PS/B	**Digital Pad Supply Voltage for Domain B** Connect decoupling capacitors to adjacent V_{DDP}/V_{SS} pin pairs as close as possible to the pins. *Note: The on-chip voltage regulators and all ports except P5, P6, and P15 are fed from supply voltage V_{DDPB}.*
1, 26, 51, 76	V_{SS}	-	PS/--	**Digital Ground** All V_{SS} pins must be connected to the ground-line or ground-plane. *Note: Also the exposed pad is connected to V_{SS}. The respective board area must be connected to ground (if soldered) or left free.*

1) To generate the reference clock output for bus timing measurement, f_{SYS} must be selected as source for EXTCLK and P2.8 must be selected as output pin. Also the high-speed clock pad must be enabled. This configuration is referred to as reference clock output signal CLKOUT.

2) Pin TRef was used to control the core voltage generation in step AA. For that step, pin TRef must be connected to V_{DDPB}.
This connection is no more required from step AB on. For the current step, pin TRef is logically not connected. Future derivatives will feature an additional general purpose IO pin at this position.

3 Functional Description

The architecture of the XC2365 combines advantages of RISC, CISC, and DSP processors with an advanced peripheral subsystem in a well-balanced design. On-chip memory blocks allow the design of compact systems-on-silicon with maximum performance suited for computing, control, and communication.

The on-chip memory blocks (program code memory and SRAM, dual-port RAM, data SRAM) and the generic peripherals are connected to the CPU by separate high-speed buses. Another bus, the LXBus, connects additional on-chip resources and external resources (see **Figure 3**). This bus structure enhances overall system performance by enabling the concurrent operation of several subsystems of the XC2365.

The block diagram gives an overview of the on-chip components and the advanced internal bus structure of the XC2365.

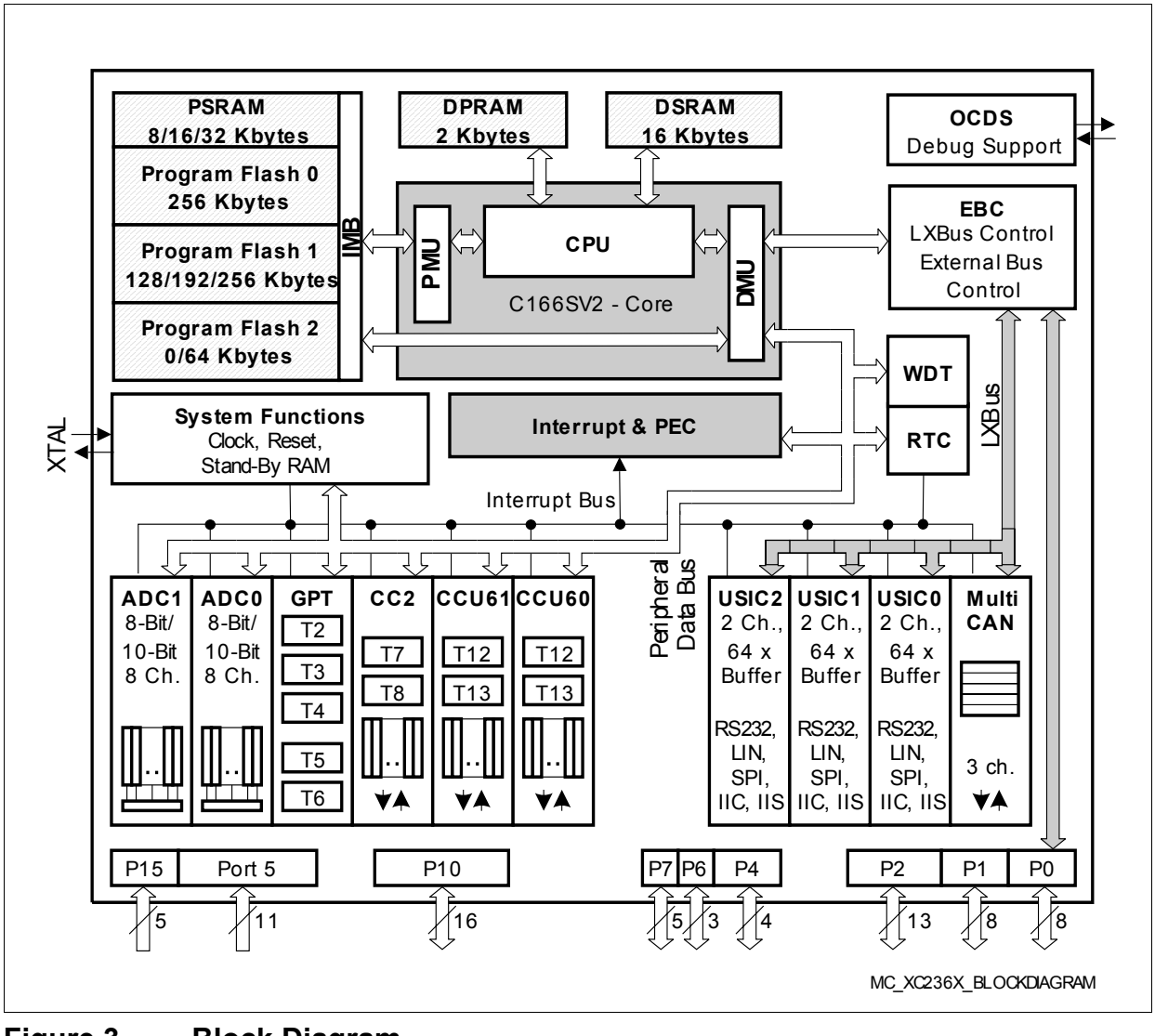

Figure 3 Block Diagram

3.2 External Bus Controller

All external memory access operations are performed by a special on-chip External Bus Controller (EBC). The EBC also controls access to resources connected to the on-chip LXBus (MultiCAN and the USIC modules). The LXBus is an internal representation of the external bus that allows access to integrated peripherals and modules in the same way as to external components.

The EBC can be programmed either to Single Chip Mode, when no external memory is required, or to an external bus mode with the following selections[1)]:

- Address Bus Width with a range of 0 … 24-bit
- Data Bus Width 8-bit or 16-bit
- Bus Operation Multiplexed or Demultiplexed

The bus interface uses Port 10 and Port 2 for addresses and data. In the demultiplexed bus modes, the lower addresses are output separately on Port 0 and Port 1. The number of active segment address lines is selectable, restricting the external address space to 8 Mbytes … 64 Kbytes. This is required when interface lines shall be assigned to Port 2.

Up to four external $\overline{CS}$ signals (three windows plus default) can be generated and output on Port 4 in order to save external glue logic. External modules can be directly connected to the common address/data bus and their individual select lines.

Important timing characteristics of the external bus interface are programmable (with registers TCONCSx/FCONCSx) to allow the user to adapt it to a wide range of different types of memories and external peripherals.
Access to very slow memories or modules with varying access times is supported by a special ‘Ready’ function. The active level of the control input signal is selectable.

In addition, up to four independent address windows may be defined (using registers ADDRSELx) to control access to resources with different bus characteristics. These address windows are arranged hierarchically where window 4 overrides window 3, and window 2 overrides window 1. All accesses to locations not covered by these four address windows are controlled by TCONCS0/FCONCS0. The currently active window can generate a chip select signal.

The external bus timing is based on the rising edge of the reference clock output CLKOUT. The external bus protocol is compatible with that of the standard C166 Family.

1) Bus modes are switched dynamically if several address windows with different mode settings are used.

3.4 Interrupt System

With a minimum interrupt response time of 7/11[1)] CPU clocks (in the case of internal program execution), the XC2365 can react quickly to the occurrence of non-deterministic events.

The architecture of the XC2365 supports several mechanisms for fast and flexible response to service requests; these can be generated from various sources internal or external to the microcontroller. Any of these interrupt requests can be programmed to be serviced by the Interrupt Controller or by the Peripheral Event Controller (PEC).

Where in a standard interrupt service the current program execution is suspended and a branch to the interrupt vector table is performed, just one cycle is ‘stolen’ from the current CPU activity to perform a PEC service. A PEC service implies a single byte or word data transfer between any two memory locations with an additional increment of either the PEC source pointer, the destination pointer, or both. An individual PEC transfer counter is implicitly decremented for each PEC service except when performing in the continuous transfer mode. When this counter reaches zero, a standard interrupt is performed to the corresponding source-related vector location. PEC services are particularly well suited to supporting the transmission or reception of blocks of data. The XC2365 has eight PEC channels, each whith fast interrupt-driven data transfer capabilities.

Each of the possible interrupt nodes has a separate control register containing an interrupt request flag, an interrupt enable flag and an interrupt priority bitfield. Each node can be programmed by its related register to one of sixteen interrupt priority levels. Once accepted by the CPU, an interrupt service can only be interrupted by a higher-priority service request. For standard interrupt processing, each possible interrupt node has a dedicated vector location.

Fast external interrupt inputs can service external interrupts with high-precision requirements. These fast interrupt inputs feature programmable edge detection (rising edge, falling edge, or both edges).

Software interrupts are supported by the ‘TRAP’ instruction in combination with an individual trap (interrupt) number.

Table 6 shows all of the possible XC2365 interrupt sources and the corresponding hardware-related interrupt flags, vectors, vector locations and trap (interrupt) numbers.

Note: Interrupt nodes which are not assigned to peripherals (unassigned nodes) may be used to generate software-controlled interrupt requests by setting the respective interrupt request bit (xIR).

1) Depending if the jump cache is used or not.

3.6 Capture/Compare Unit (CAPCOM2)

The CAPCOM2 unit supports generation and control of timing sequences on up to 16 channels with a maximum resolution of one system clock cycle (eight cycles in staggered mode). The CAPCOM2 unit is typically used to handle high-speed I/O tasks such as pulse and waveform generation, pulse width modulation (PWM), digital to analog (D/A) conversion, software timing, or time recording with respect to external events.

Two 16-bit timers (T7/T8) with reload registers provide two independent time bases for the capture/compare register array.

The input clock for the timers is programmable to a number of prescaled values of the internal system clock. It may also be derived from an overflow/underflow of timer T6 in module GPT2. This provides a wide range for the timer period and resolution while allowing precise adjustments for application-specific requirements. An external count input for CAPCOM2 timer T7 allows event scheduling for the capture/compare registers with respect to external events.

The capture/compare register array contains 16 dual purpose capture/compare registers. Each may be individually allocated to either CAPCOM2 timer T7 or T8 and programmed for a capture or compare function.
12 registers of the CAPCOM2 module have one port pin associated with it. This serves as an input pin to trigger the capture function or as an output pin to indicate the occurrence of a compare event.

Table 8 Compare Modes (CAPCOM2)

Compare Modes	Function
Mode 0	Interrupt-only compare mode; Several compare interrupts per timer period are possible
Mode 1	Pin toggles on each compare match; Several compare events per timer period are possible
Mode 2	Interrupt-only compare mode; Only one compare interrupt per timer period is generated
Mode 3	Pin set ‘1’ on match; pin reset ‘0’ on compare timer overflow; Only one compare event per timer period is generated
Double Register Mode	Two registers operate on one pin; Pin toggles on each compare match; Several compare events per timer period are possible
Single Event Mode	Generates single edges or pulses; Can be used with any compare mode

When a capture/compare register has been selected for capture mode, the current contents of the allocated timer will be latched (‘captured’) into the capture/compare register in response to an external event at the port pin associated with this register. In addition, a specific interrupt request for this capture/compare register is generated. Either a positive, a negative, or both a positive and a negative external signal transition at the pin can be selected as the triggering event.

The contents of all registers selected for one of the five compare modes are continuously compared with the contents of the allocated timers.

When a match occurs between the timer value and the value in a capture/compare register, specific actions will be taken based on the compare mode selected.

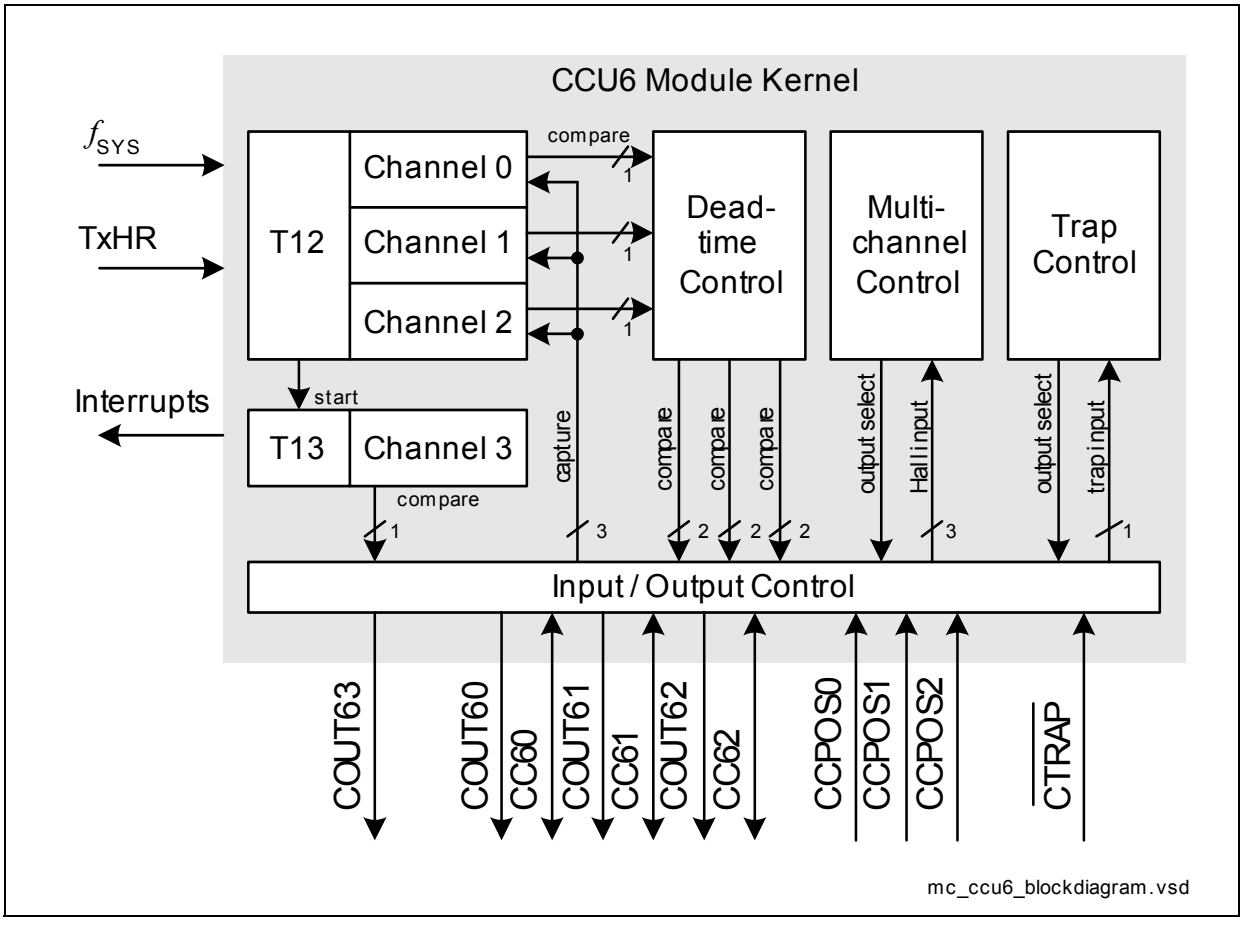

Figure 6 CCU6 Block Diagram

Timer T12 can work in capture and/or compare mode for its three channels. The modes can also be combined. Timer T13 can work in compare mode only. The multi-channel control unit generates output patterns that can be modulated by timer T12 and/or timer T13. The modulation sources can be selected and combined for signal modulation.

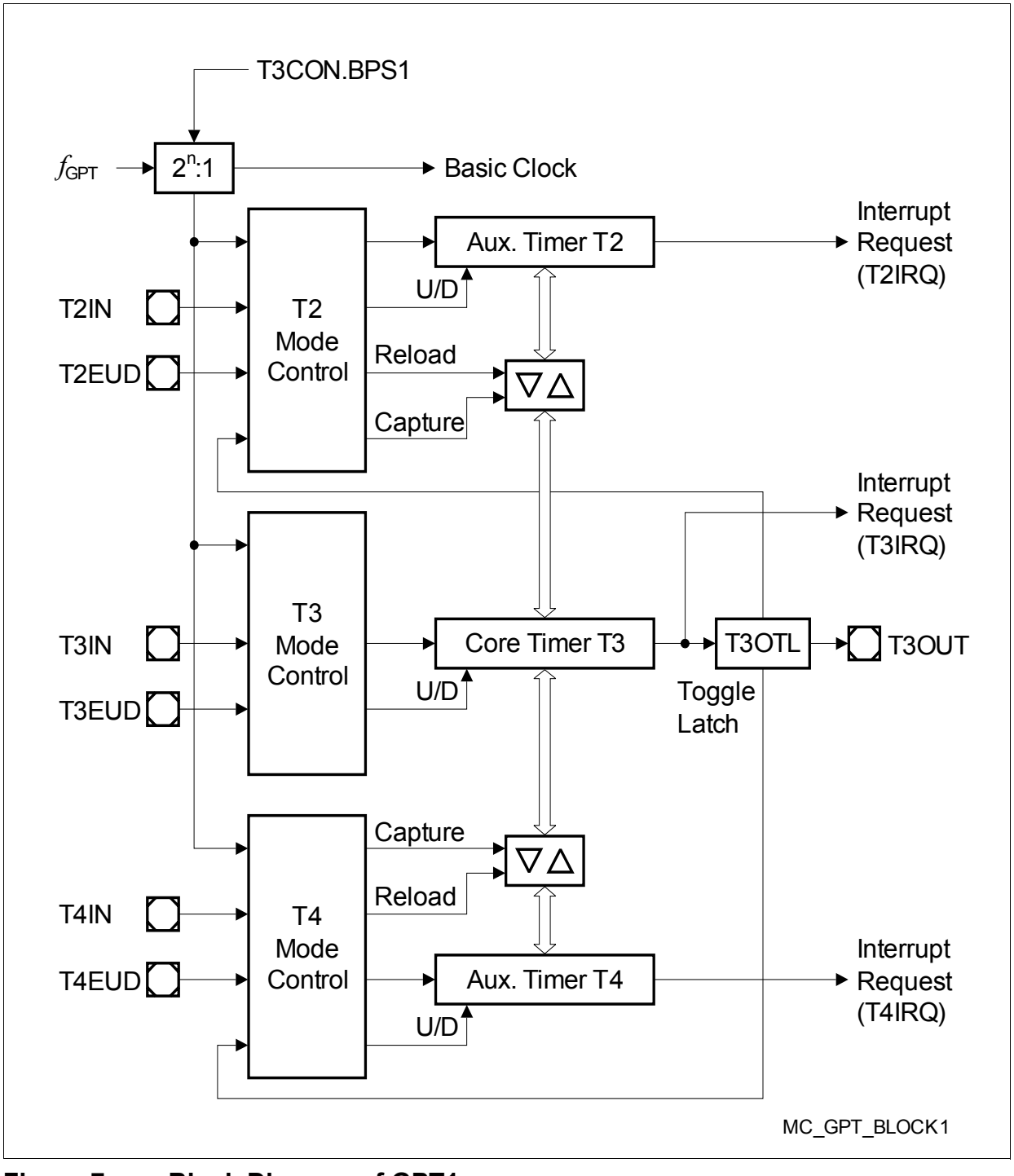

Figure 7 Block Diagram of GPT1

The RTC module can be used for different purposes:

- System clock to determine the current time and date
- Cyclic time-based interrupt, to provide a system time tick independent of CPU frequency and other resources
- 48-bit timer for long-term measurements
- Alarm interrupt at a defined time

3.11 Universal Serial Interface Channel Modules (USIC)

The XC2365 includes three USIC modules (USIC0, USIC1, USIC2), each providing two serial communication channels.

The Universal Serial Interface Channel (USIC) module is based on a generic data shift and data storage structure which is identical for all supported serial communication protocols. Each channel supports complete full-duplex operation with a basic data buffer structure (one transmit buffer and two receive buffer stages). In addition, the data handling software can use FIFOs.

The protocol part (generation of shift clock/data/control signals) is independent of the general part and is handled by protocol-specific preprocessors (PPPs).

The USIC's input/output lines are connected to pins by a pin routing unit. The inputs and outputs of each USIC channel can be assigned to different interface pins, providing great flexibility to the application software. All assignments can be made during runtime.

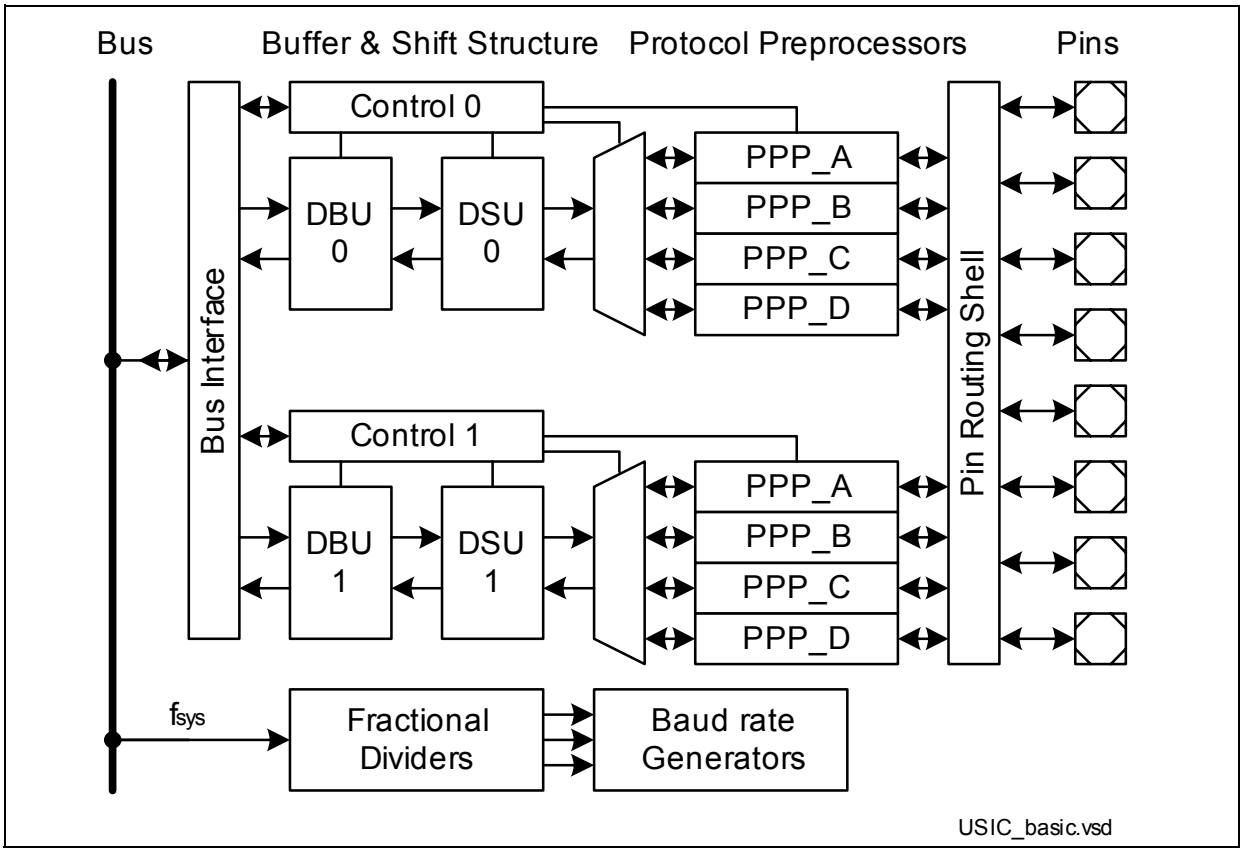

Figure 10 General Structure of a USIC Module

The regular structure of the USIC module brings the following advantages:

- Higher flexibility through configuration with same look-and-feel for data management
- Reduced complexity for low-level drivers serving different protocols
- Wide range of protocols with improved performances (baud rate, buffer handling)

3.12 MultiCAN Module

The MultiCAN module contains three independently operating CAN nodes with Full-CAN functionality which are able to exchange Data and Remote Frames using a gateway function. Transmission and reception of CAN frames is handled in accordance with CAN specification V2.0 B (active). Each CAN node can receive and transmit standard frames with 11-bit identifiers as well as extended frames with 29-bit identifiers.

All CAN nodes share a common set of 64 message objects. Each message object can be individually allocated to one of the CAN nodes. Besides serving as a storage container for incoming and outgoing frames, message objects can be combined to build gateways between the CAN nodes or to set up a FIFO buffer.

The message objects are organized in double-chained linked lists, where each CAN node has its own list of message objects. A CAN node stores frames only into message objects that are allocated to its own message object list and it transmits only messages belonging to this message object list. A powerful, command-driven list controller performs all message object list operations.

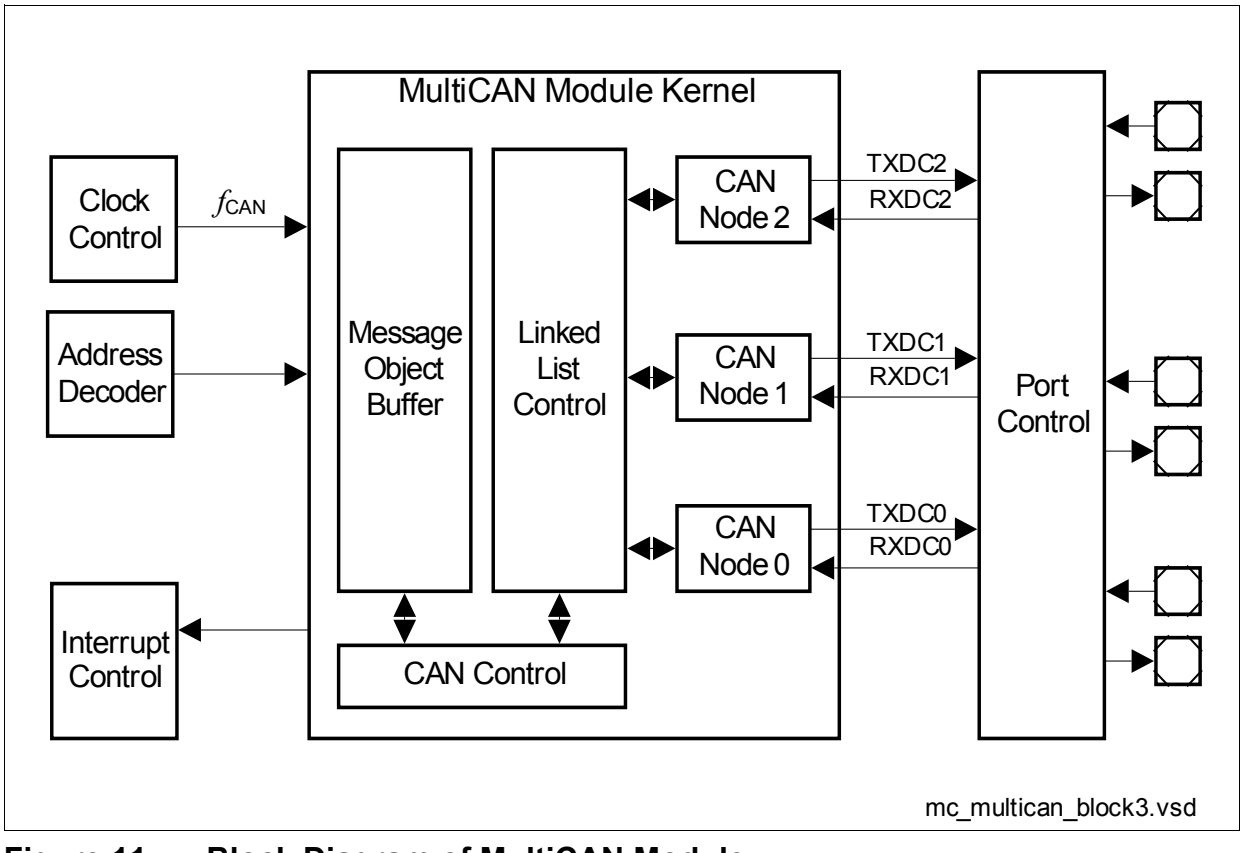

Figure 11 Block Diagram of MultiCAN Module

Parameter Interpretation

The parameters listed in the following include both the characteristics of the XC2365 and its demands on the system. To aid in correctly interpreting the parameters when evaluating them for a design, they are marked accordingly in the column “Symbol”:

CC (**C**ontroller **C**haracteristics):
The logic of the XC2365 provides signals with the specified characteristics.

SR (**S**ystem **R**equirement):
The external system must provide signals with the specified characteristics to the XC2365.

4.2.1 DC Parameters for Upper Voltage Area

These parameters apply to the upper IO voltage range, 4.5 V ≤ V_{DDP} ≤ 5.5 V.

Table 14 DC Characteristics for Upper Voltage Range (Operating Conditions apply)[1)]

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input low voltage (all except XTAL1)	V_{IL} SR	-0.3	–	0.3 × V_{DDP}	V	–
Input high voltage (all except XTAL1)	V_{IH} SR	0.7 × V_{DDP}	–	V_{DDP} + 0.3	V	–
Input Hysteresis[2)]	HYS CC	0.11 × V_{DDP}	–	–	V	V_{DDP} in [V], Series resistance = 0 Ω
Output low voltage	V_{OL} CC	–	–	1.0	V	$I_{OL} \le I_{OLmax}$[3)]
Output low voltage	V_{OL} CC	–	–	0.4	V	$I_{OL} \le I_{OLnom}$[3)4)]
Output high voltage[5)]	V_{OH} CC	V_{DDP} - 1.0	–	–	V	$I_{OH} \ge I_{OHmax}$[3)]
Output high voltage[5)]	V_{OH} CC	V_{DDP} - 0.4	–	–	V	$I_{OH} \ge I_{OHnom}$[3)4)]
Input leakage current (Port 5, Port 15)[6)]	I_{OZ1} CC	–	±10	±200	nA	0 V < V_{IN} < V_{DDP}
Input leakage current (all other)[6)7)]	I_{OZ2} CC	–	±0.2	±5	µA	$T_J \le$ 110°C, 0.45 V < V_{IN} < V_{DDP}
Input leakage current (all other)[6)7)]	I_{OZ2} CC	–	±0.2	±15	µA	$T_J \le$ 150°C, 0.45 V < V_{IN} < V_{DDP}
Pull level keep current	I_{PLK}	–	–	±30	µA	$V_{PIN} \ge V_{IH}$ (up)[8)] $V_{PIN} \le V_{IL}$ (dn)
Pull level force current	I_{PLF}	±250	–	–	µA	$V_{PIN} \le V_{IL}$ (up)[8)] $V_{PIN} \ge V_{IH}$ (dn)
Pin capacitance[9)] (digital inputs/outputs)	C_{IO} CC	–	–	10	pF	

1) Keeping signal levels within the limits specified in this table ensures operation without overload conditions. For signal levels outside these specifications, also refer to the specification of the overload current I_{OV}.

2) Not subject to production test - verified by design/characterization. Hysteresis is implemented to avoid metastable states and switching due to internal ground bounce. It cannot suppress switching due to external system noise under all conditions.
3) The maximum deliverable output current of a port driver depends on the selected output driver mode, see **Table 13, Current Limits for Port Output Drivers**. The limit for pin groups must be respected.
4) As a rule, with decreasing output current the output levels approach the respective supply level ($V_{OL} \rightarrow V_{SS}$, $V_{OH} \rightarrow V_{DDP}$). However, only the levels for nominal output currents are verified.
5) This specification is not valid for outputs which are switched to open drain mode. In this case the respective output will float and the voltage is determined by the external circuit.
6) An additional error current (I_{INJ}) will flow if an overload current flows through an adjacent pin. Please refer to the definition of the overload coupling factor K_{OV}.
7) The given values are worst-case values. In production test, this leakage current is only tested at 125°C; other values are ensured by correlation. For derating, please refer to the following descriptions:
   Leakage derating depending on temperature (T_J = junction temperature [°C]):
   I_{OZ} = 0.05 × $e^{(1.5 + 0.028 \times TJ)}$ [µA]. For example, at a temperature of 130°C the resulting leakage current is 8.54 µA.
   Leakage derating depending on voltage level (DV = V_{DDP} - V_{PIN} [V]):
   I_{OZ} = $I_{OZtempmax}$ - (1.6 × DV) [µA]
   This voltage derating formula is an approximation which applies for maximum temperature.
   Because pin P2.8 is connected to two pads (standard pad and high-speed clock pad), it has twice the normal leakage.
8) Keep current: Limit the current through this pin to the indicated value so that the enabled pull device can keep the default pin level: $V_{PIN} \geq V_{IH}$ for a pullup; $V_{PIN} \leq V_{IL}$ for a pulldown.
   Force current: Drive the indicated minimum current through this pin to change the default pin level driven by the enabled pull device: $V_{PIN} \leq V_{IL}$ for a pullup; $V_{PIN} \geq V_{IH}$ for a pulldown.
   These values apply to the fixed pull-devices in dedicated pins and to the user-selectable pull-devices in general purpose IO pins.
9) Not subject to production test - verified by design/characterization.
   Because pin P2.8 is connected to two pads (standard pad and high-speed clock pad), it has twice the normal capacitance.

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6) An additional error current (I_{INJ}) will flow if an overload current flows through an adjacent pin. Please refer to the definition of the overload coupling factor K_{OV}.
   The leakage current value is not tested in the lower voltage range but only in the upper voltage range. This parameter is ensured by correlation.
7) The given values are worst-case values. In production test, this leakage current is only tested at 125°C; other values are ensured by correlation. For derating, please refer to the following descriptions:
   Leakage derating depending on temperature (T_J = junction temperature [°C]):
   I_{OZ} = 0.03 × $e^{(1.35 + 0.028 \times TJ)}$ [µA]. For example, at a temperature of 130°C the resulting leakage current is 4.41 µA.
   Leakage derating depending on voltage level (DV = V_{DDP} - V_{PIN} [V]):
   I_{OZ} = $I_{OZtempmax}$ - (1.3 × DV) [µA]
   This voltage derating formula is an approximation which applies for maximum temperature.
   Because pin P2.8 is connected to two pads (standard pad and high-speed clock pad), it has twice the normal leakage.
8) Keep current: Limit the current through this pin to the indicated value so that the enabled pull device can keep the default pin level: $V_{PIN} \geq V_{IH}$ for a pullup; $V_{PIN} \leq V_{IL}$ for a pulldown.
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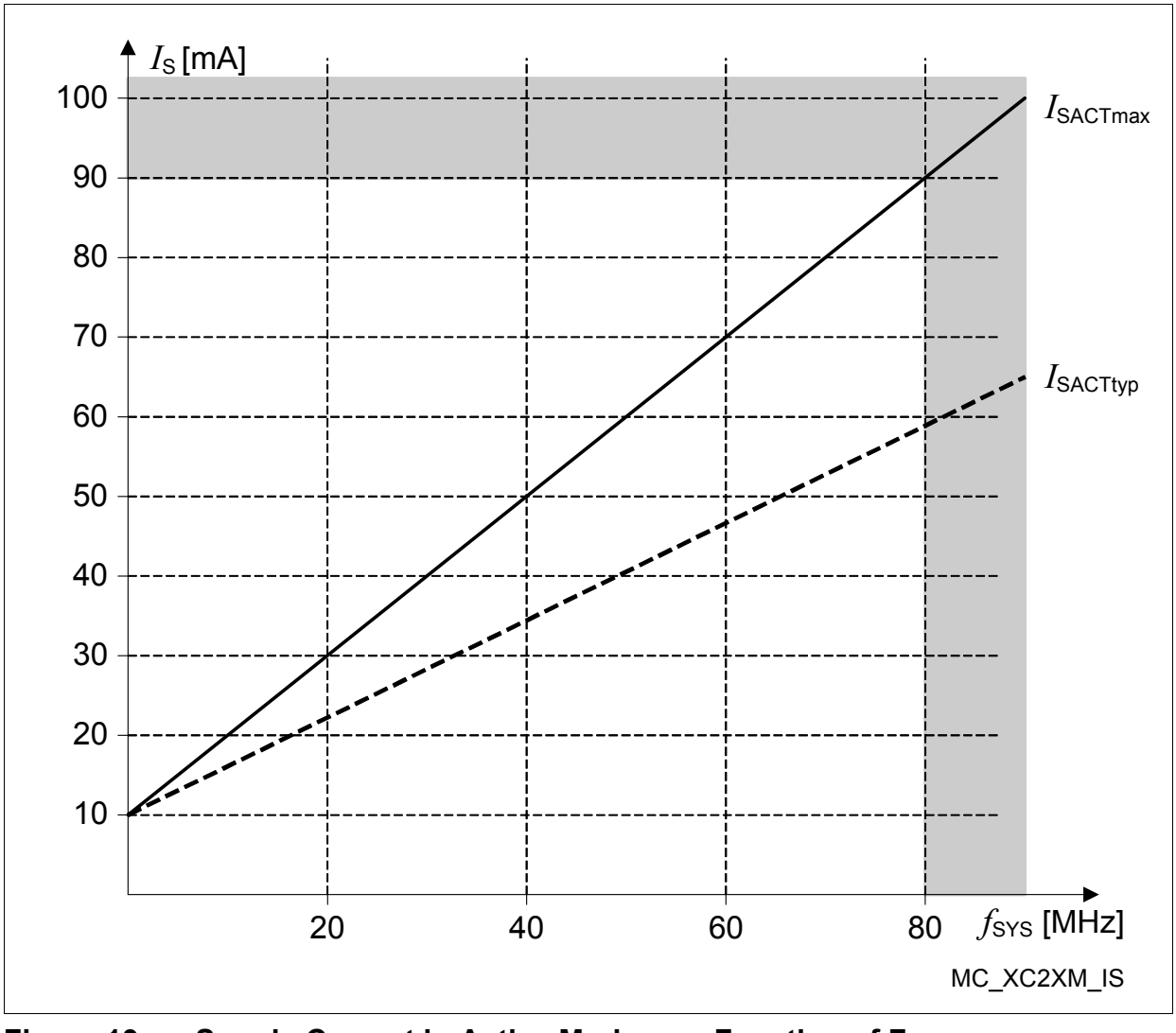

Figure 13 Supply Current in Active Mode as a Function of Frequency

Table 24 Flash Access Waitstates

Required Waitstates	System Frequency Range
4 WS (WSFLASH = 100_B)	$f_{SYS} \leq f_{SYSmax}$
3 WS (WSFLASH = 011_B)	$f_{SYS} \leq 17$ MHz
2 WS (WSFLASH = 010_B)	$f_{SYS} \leq 13$ MHz
1 WS (WSFLASH = 001_B)	$f_{SYS} \leq 8$ MHz
0 WS (WSFLASH = 000_B)	Forbidden! Must not be selected!

Note: The maximum achievable system frequency is limited by the properties of the respective derivative.

Variable Memory Cycles

External bus cycles of the XC2365 are executed in five consecutive cycle phases (AB, C, D, E, F). The duration of each cycle phase is programmable (via the TCONCSx registers) to adapt the external bus cycles to the respective external module (memory, peripheral, etc.).

The duration of the access phase can optionally be controlled by the external module using the READY handshake input.

This table provides a summary of the phases and the ranges for their length.

Table 28 Programmable Bus Cycle Phases (see timing diagrams)

Bus Cycle Phase	Parameter	Valid Values	Unit
Address setup phase, the standard duration of this phase (1 … 2 TCS) can be extended by 0 … 3 TCS if the address window is changed	tpAB	1 … 2 (5)	TCS
Command delay phase	tpC	0 … 3	TCS
Write Data setup/MUX Tristate phase	tpD	0 … 1	TCS
Access phase	tpE	1 … 32	TCS
Address/Write Data hold phase	tpF	0 … 3	TCS

Note: The bandwidth of a parameter (from minimum to maximum value) covers the whole operating range (temperature, voltage) as well as process variations. Within a given device, however, this bandwidth is smaller than the specified range. This is also due to interdependencies between certain parameters. Some of these interdependencies are described in additional notes (see standard timing).

Timing values are listed in **Table 29** and **Table 30**. The shaded parameters have been verified by characterization. They are not subject to production test.

5 Package and Reliability

In addition to the electrical parameters, the following specifcations ensure proper integration of the XC2365 into the target system.

5.1 Packaging

These parameters specify the packaging rather than the silicon.

Table 34 Package Parameters (PG-LQFP-100-3)

Parameter	Symbol	Limit Values		Unit	Notes
		Min.	Max.		
Exposed Pad Dimension	Ex × Ey	–	6.2 × 6.2	mm	–
Power Dissipation	P_{DISS}	–	1.0	W	–
Thermal resistance Junction-Ambient	$R_{\Theta JA}$	–	49	K/W	No thermal via[1)]
			37	K/W	4-layer, no pad[2)]
			22	K/W	4-layer, pad[3)]

1) Device mounted on a 2-layer JEDEC board (according to JESD 51-3) or a 4-layer board without thermal vias; exposed pad not soldered.

2) Device mounted on a 4-layer JEDEC board (according to JESD 51-7) with thermal vias; exposed pad not soldered.

3) Device mounted on a 4-layer JEDEC board (according to JESD 51-7) with thermal vias; exposed pad soldered to the board.